

Datasheet revision 1.4 www.chipquik.com

Heat Sink Compound - Grey Ultra Conductive 20g Syringe 10cc

Product Highlights

- Lead-Free / RoHS 3 Compliant / REACH Compliant
- Ultra High-Density Thermal Paste. Grey, noncuring, flowable, thermally conductive heat sink compound. Heavily filled with heat-conductive metal oxide. Provides extremely high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (7 x 10¹² ohm-cm)



Viscosity: 95,000 cP (95,000 mPa·s)

Density:

Thermal Conductivity:

Thermal Resistance:

Electrical Volume Resistivity:

Dielectric Strength:

2.5g/cc

4.3 W/m·K

0.06 °C*cm²/W

7 x 10¹² ohm-cm

0.67 MV/m (17V/mil)

Operating Temperature (Continuous): -40 to 150°C (-40 to 302°F)

Operating Temperature (Peak): 200°C (392°F)
Size: 20g Syringe (10cc)



Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life

>24 months

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m·K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G